MCP1630/MCP1630V

High-Speed, Microcontroller-Adaptable, Pulse Width Modulator

Features

- High-Speed PWM Operation (12 ns Current Sense to Output Delay)
- Operating Temperature Range:
  - -40°C to +125°C
- Precise Peak Current Limit (±5%) (**MCP1630**)
- Voltage Mode and Average Current Mode Control (**MCP1630V**)
- CMOS Output Driver (drives MOSFET driver or low-side N-channel MOSFET directly)
- External Oscillator Input (from PIC® Microcontroller (MCU))
- External Voltage Reference Input (for adjustable voltage or current output application)
- Peak Current Mode Operation > 1 MHz
- Low Operating Current: 2.8 mA (typ.)
- Fast Output Rise and Fall Times: 5.9 ns and 6.2 ns
- Undervoltage Lockout (UVLO) Protection
- Output Short Circuit Protection
- Overtemperature Protection

Applications

- Intelligent Power Systems
- Smart Battery Charger Applications
- Multiple Output/Multiple Phase Converters
- Output Voltage Calibration
- AC Power Factor Correction
- VID Capability (programmed and calibrated by PIC® microcontroller)
- Buck/Boost/Buck-Boost/SEPIC/Flyback/Isolated Converters
- Parallel Power Supplies

Related Literature

- “MCP1630 NiMH Demo Board User’s Guide”, Microchip Technology Inc., DS51505, 2004
- “MCP1630 Low-Cost Li-Ion Battery Charger User’s Guide”, Microchip Technology Inc., DS51555, 2005
- “MCP1630 Li-Ion Multi-Bay Battery Charger User’s Guide”, Microchip Technology Inc., DS51515, 2005
- “MCP1630 Dual Buck Demo Board User’s Guide”, Microchip Technology Inc., DS51531, 2005

Description

The MCP1630/V is a high-speed Pulse Width Modulator (PWM) used to develop intelligent power systems. When used with a microcontroller unit (MCU), the MCP1630/V will control the power system duty cycle to provide output voltage or current regulation. The MCU can be used to adjust output voltage or current, switching frequency, maximum duty cycle and other features that make the power system more intelligent.

Typical applications include smart battery chargers, intelligent power systems, brick dc/dc converters, ac power-factor correction, multiple output power supplies, multi-phase power supplies and more.

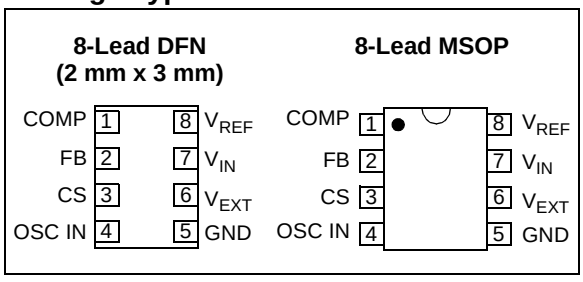
The MCP1630/V inputs were developed to be easily attached to the I/O of a MCU. The MCU supplies the oscillator and reference to the MCP1630/V to provide the most flexible and adaptable power system. The power system switching frequency and maximum duty cycle are set using the I/O of the MCU. The reference input can be external, a D/A Converter (DAC) output or as simple as an I/O output from the MCU. This enables the power system to adapt to many external signals and variables in order to optimize performance and facilitate calibration.

When operating in Current mode, a precise limit is set on the peak current. With the fast comparator speed (typically 12 ns), the MCP1630 is capable of providing a tight limit on the maximum switch current over a wide input voltage range when compared to other high-speed PWM controllers.

For Voltage mode or Average Current mode applications, the MCP1630V provides a larger range for the external ramp voltage.

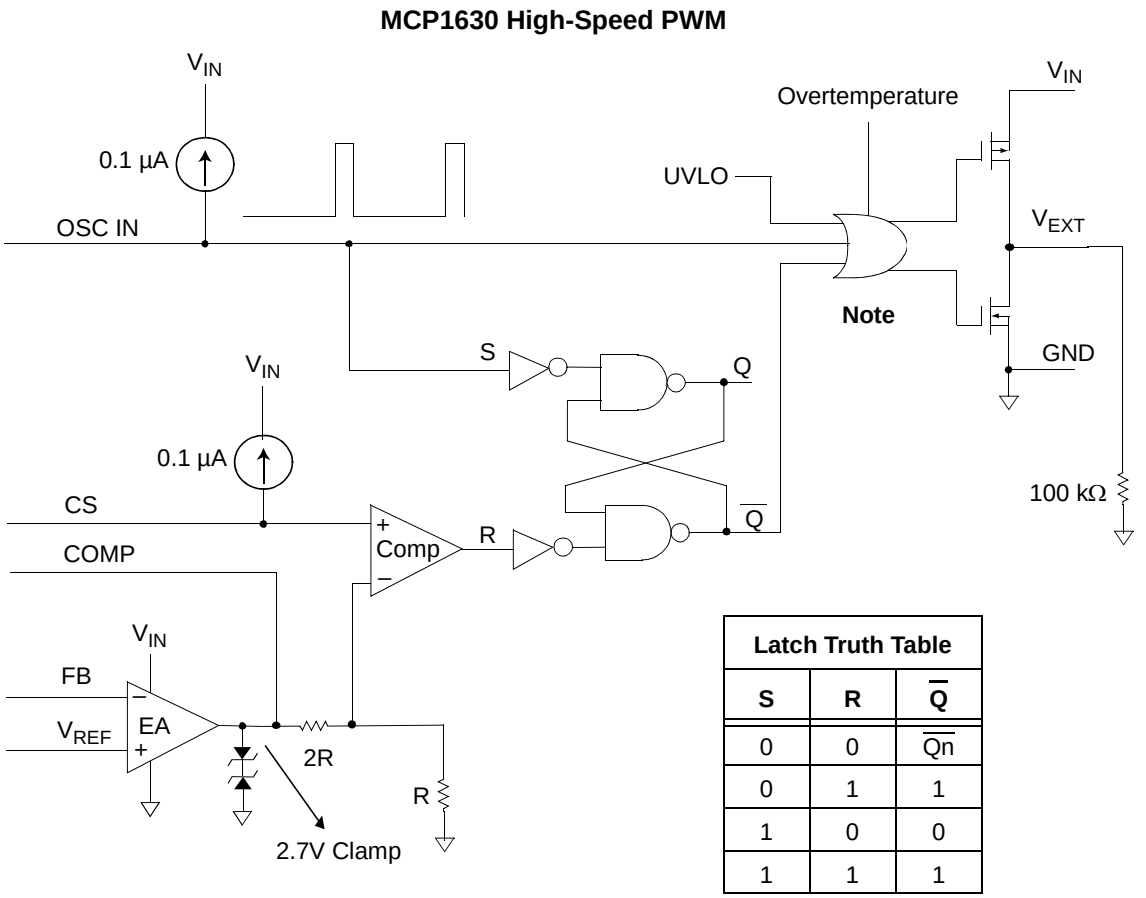
Additional protection features include: UVLO, overtemperature and overcurrent.

Package Type



© 2004-2013 Microchip Technology Inc.

Functional Block Diagram – MCP1630



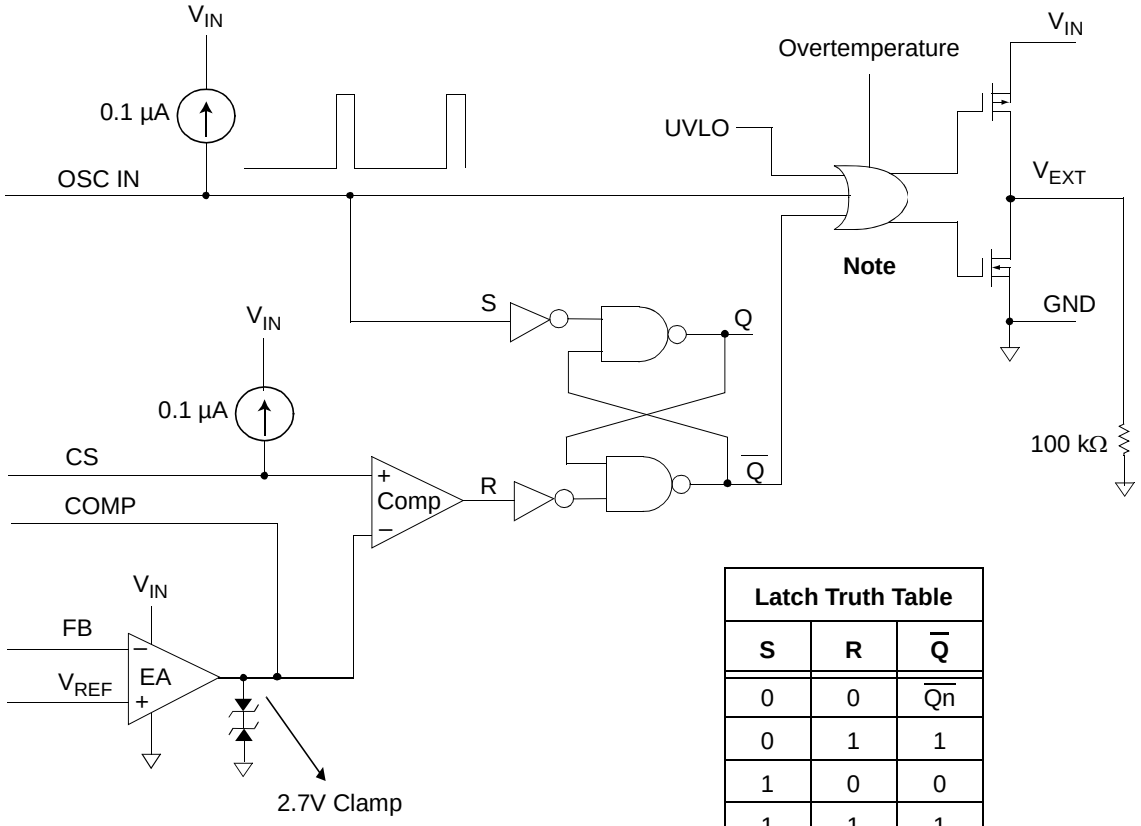
Latch Truth Table		
S	**R**	**$\overline{Q}$**
0	0	$\overline{Qn}$
0	1	1
1	0	0
1	1	1

Note: During overtemperature, V_{EXT} driver is high-impedance.

© 2004-2013 Microchip Technology Inc.

Functional Block Diagram – MCP1630V

MCP1630V High-Speed PWM

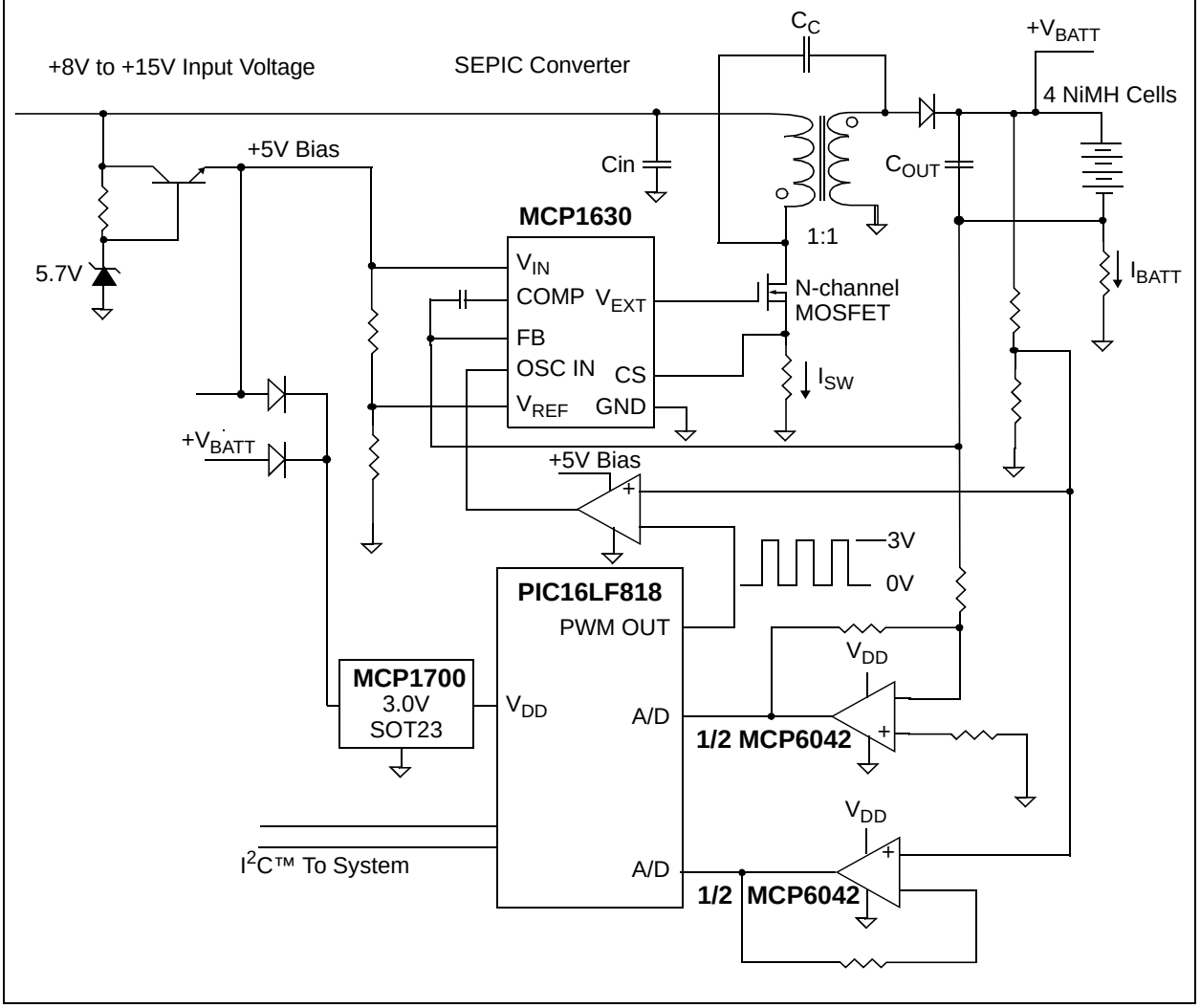


Latch Truth Table		
S	**R**	$\overline{\mathbf{Q}}$
0	0	$\overline{Qn}$
0	1	1
1	0	0
1	1	1

Note: During overtemperature, V_{EXT} driver is high-impedance.

Typical Application Circuit – MCP1630

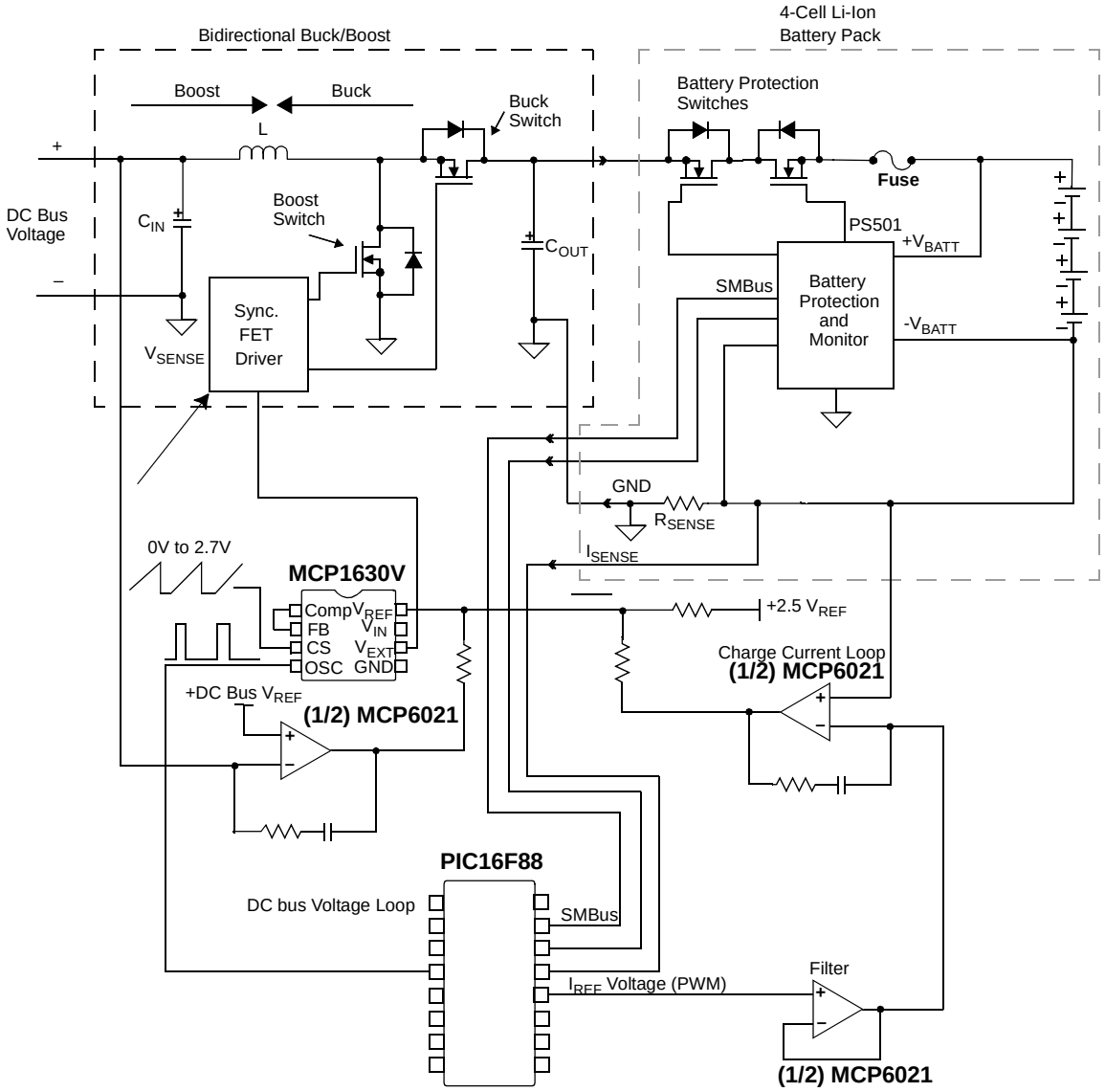
MCP1630 NiMH Battery Charger and Fuel Gauge Application Diagram



© 2004-2013 Microchip Technology Inc.

Typical Application Circuit - MCP1630V

Bidirectional Power Converter/Battery Charger for 4-Series Cell Li-Ion Batteries



1.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings †

V_{DD}.....6.0V
Maximum Voltage on Any Pin ..(V_{GND} - 0.3)V to (V_{IN} + 0.3)V
V_{EXT} Short Circuit Current .....Internally Limited
Storage temperature .....-65°C to +150°C
Maximum Junction Temperature, T_J .....+150°C
Continuous Operating Temperature Range ..-40°C to +125°C
ESD protection on all pins, HBM..... 3 kV

† **Notice:** Stresses above those listed under "Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operational listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

AC/DC CHARACTERISTICS

Electrical Specifications: Unless otherwise noted, V_{IN} = 3.0V to 5.5V, F_{OSC} = 1 MHz with 10% Duty Cycle, C_{IN} = 0.1 µF, V_{IN} for typical values = 5.0V, T_A = -40°C to +125°C.

Parameters	Sym	Min	Typ	Max	Units	Conditions
Input Voltage						
Input Operating Voltage	V_{IN}	3.0	—	5.5	V	
Input Quiescent Current	$I(V_{IN})$	—	2.8	4.5	mA	I_{EXT} = 0 mA, $F_{OSC\ IN}$ = 0 Hz
Oscillator Input						
External Oscillator Range	F_{OSC}	—	—	1	MHz	**Note 1**
Min. Oscillator High Time Min. Oscillator Low Time	T_{OH_MIN} T_{OL_MIN}	—	10		ns	
Oscillator Rise Time	T_{RISE}	0.01	—	10	µs	**Note 2**
Oscillator Fall Time	T_{FALL}	0.01	—	10	µs	**Note 2**
Oscillator Input Voltage Low	V_L	—	—	0.8	V	
Oscillator Input Voltage High	V_H	2.0	—	—	V	
Oscillator Input Capacitance	C_{OSC}		5		pf	
External Reference Input						
Reference Voltage Input	V_{REF}	0	—	V_{IN}	V	**Note 2, Note 3**
Error Amplifier						
Input Offset Voltage	V_{OS}	-4	0.1	+4	mV	
Error Amplifier PSRR	PSRR	80	99	—	dB	V_{IN} = 3.0V to 5.0V, V_{CM} = 1.2V
Common Mode Input Range	V_{CM}	GND - 0.3	—	V_{IN}	V	**Note 2, Note 3**
Common Mode Rejection Ratio		—	80	—	dB	V_{IN} = 5V, V_{CM} = 0V to 2.5V
Open-loop Voltage Gain	A_{VOL}	85	95	—	dB	R_L = 5 kΩ to V_{IN}/2, 100 mV < V_{EAOUT} < V_{IN} - 100 mV, V_{CM} = 1.2V
Low-level Output	V_{OL}	—	25	GND + 50	mV	RL = 5 kΩ to V_{IN}/2
Gain Bandwidth Product	GBWP	—	3.5	—	MHz	V_{IN} = 5V
Error Amplifier Sink Current	I_{SINK}	5	11	—	mA	V_{IN} = 5V, V_{REF} = 1.2V, V_{FB} = 1.4V, V_{COMP} = 2.0V
Error Amplifier Source Current	I_{SOURCE}	-2	-9	—	mA	V_{IN} = 5V, V_{REF} = 1.2V, V_{FB} = 1.0V, V_{COMP} = 2.0V, Absolute Value

Note 1: Capable of higher frequency operation depending on minimum and maximum duty cycles needed.

2: External oscillator input (OSC IN) rise and fall times between 10 ns and 10 µs used for characterization testing. Signal levels between 0.8V and 2.0V with rise and fall times measured between 10% and 90% of maximum and minimum values. Not production tested.

3: The reference input of the internal amplifier is capable of rail-to-rail operation.

© 2004-2013 Microchip Technology Inc.

AC/DC CHARACTERISTICS (CONTINUED)

Electrical Specifications: Unless otherwise noted, V_{IN} = 3.0V to 5.5V, F_{OSC} = 1 MHz with 10% Duty Cycle, C_{IN} = 0.1 µF, V_{IN} for typical values = 5.0V, T_A = -40°C to +125°C.

Parameters	Sym	Min	Typ	Max	Units	Conditions
Current Sense Input						
Maximum Current Sense Signal MCP1630	V_{CS_MAX}	0.85	0.9	0.95	V	Set by maximum error amplifier clamp voltage, divided by 3.
Delay From CS to V_{EXT} MCP1630	T_{CS_VEXT}	—	12	25	ns	
Maximum Current Sense Signal MCP1630V	V_{CS_MAX}	2.55	2.7	2.85	V	V_{IN} > 4.25V Maximum CS input range limited by comparator input common mode range. $V_{CS_MAX} = V_{IN}$-1.4V
Delay From CS to V_{EXT} MCP1630V	T_{CS_VEXT}	—	17.5	35	ns	
Minimum Duty Cycle	DC_{MIN}	—	—	0	%	$V_{FB} = V_{REF}$ + 0.1V, V_{CS} = GND
Current Sense Input Bias Current	I_{CS_B}	—	-0.1	—	µA	V_{IN} = 5V
Internal Driver						
R_{DSON} P-channel	R_{DSon_P}	—	10	30	Ω	
R_{DSON} N-channel	R_{DSon_N}	—	7	30	Ω	
V_{EXT} Rise Time	T_{RISE}	—	5.9	18	ns	C_L = 100 pF Typical for V_{IN} = 3V
V_{EXT} Fall Time	T_{FALL}	—	6.2	18	ns	C_L = 100 pF Typical for V_{IN} = 3V
Protection Features						
Under Voltage Lockout	UVLO	2.7	—	3.0	V	V_{IN} falling, V_{EXT} low state when in UVLO
Under Voltage Lockout Hysteresis	$UVLO_{HYS}$	50	75	150	mV	
Thermal Shutdown	T_{SHD}	—	150	—	°C	
Thermal Shutdown Hysteresis	T_{SHD_HYS}	—	18	—	°C	

Note 1: Capable of higher frequency operation depending on minimum and maximum duty cycles needed.

2: External oscillator input (OSC IN) rise and fall times between 10 ns and 10 µs used for characterization testing. Signal levels between 0.8V and 2.0V with rise and fall times measured between 10% and 90% of maximum and minimum values. Not production tested.

3: The reference input of the internal amplifier is capable of rail-to-rail operation.

TEMPERATURE SPECIFICATIONS

Electrical Specifications: V_{IN} = 3.0V to 5.5V, F_{OSC} = 1 MHz with 10% Duty Cycle, C_{IN} = 0.1 µF. T_A = -40°C to +125°C.

Parameters	Sym	Min	Typ	Max	Units	Conditions
Temperature Ranges						
Operating Junction Temperature Range	T_A	-40	—	+125	°C	Steady state
Storage Temperature Range	T_A	-65	—	+150	°C	
Maximum Junction Temperature	T_J	—	—	+150	°C	Transient
Thermal Package Resistances						
Thermal Resistance, 8L-DFN (2 mm x 3 mm)	θ_{JA}	—	50.8	—	°C/W	Typical 4-layer board with two interconnecting vias
Thermal Resistance, 8L-MSOP	θ_{JA}	—	208	—	°C/W	Typical 4-layer board

2.0 TYPICAL PERFORMANCE CURVES

Note: The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs or tables, the data presented may be outside the specified operating range (e.g., outside specified power supply range) and therefore outside the warranted range.

Note: Unless otherwise noted, V_{IN} = 3.0V to 5.5V, F_{OSC} = 1 MHz with 10% Duty Cycle, C_{IN} = 0.1 µF, V_{IN} for typical values = 5.0V, T_A = -40°C to +125°C.

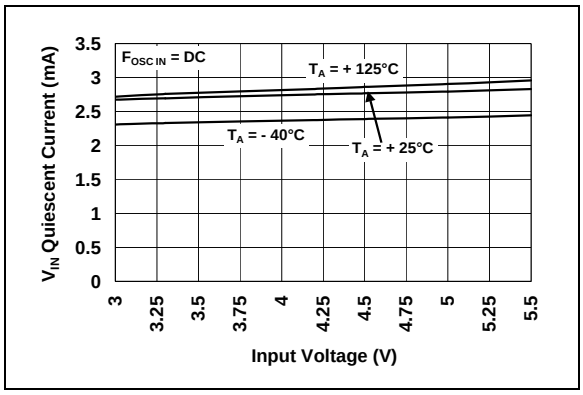


FIGURE 2-1: *Input Quiescent Current vs. Input Voltage.*

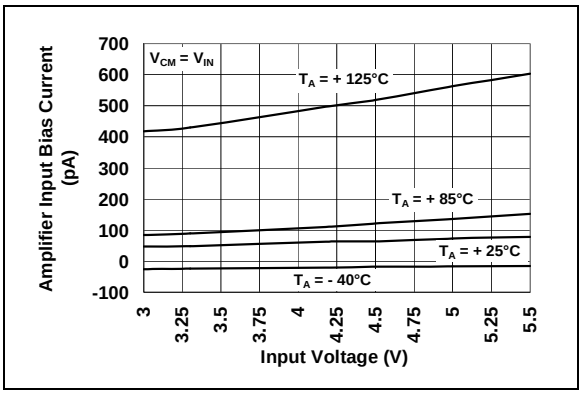


FIGURE 2-4: *Error Amplifier Input Bias Current vs. Input Voltage.*

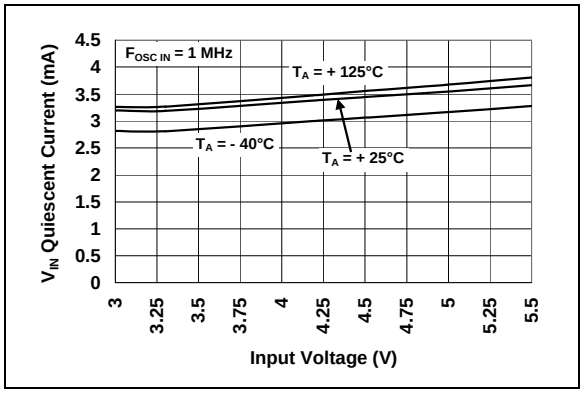


FIGURE 2-2: *Input Quiescent Current vs. Input Voltage.*

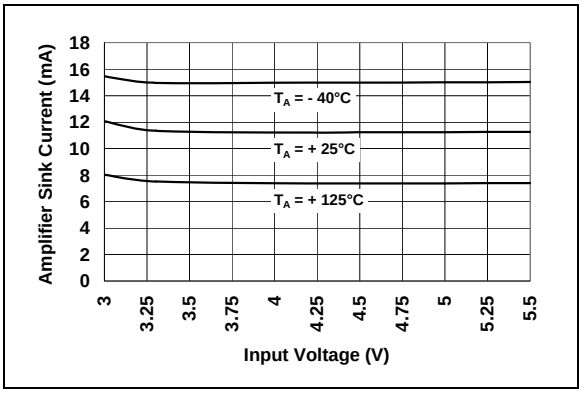


FIGURE 2-5: *Error Amplifier Sink Current vs. Input Voltage.*

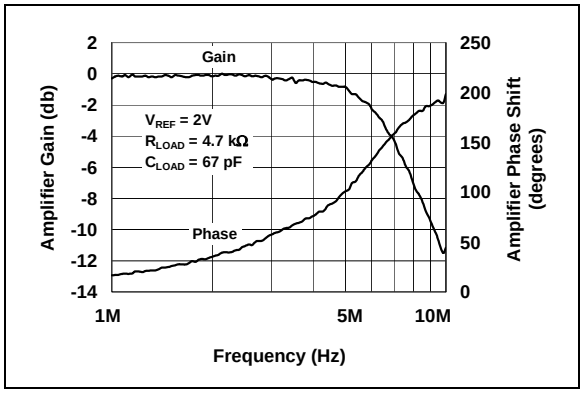


FIGURE 2-3: *Error Amplifier Frequency Response.*

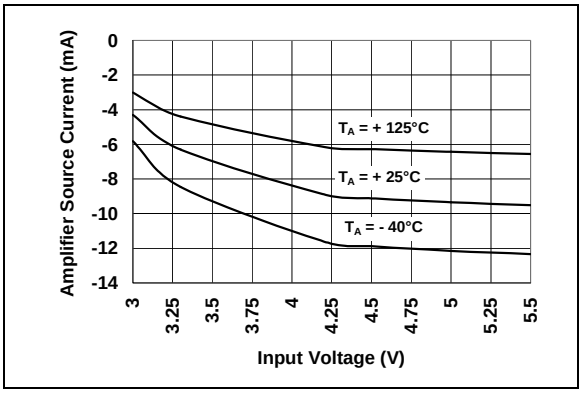


FIGURE 2-6: *Error Amplifier Source Current vs. Input Voltage.*

© 2004-2013 Microchip Technology Inc.

Note: Unless otherwise noted, V_{IN} = 3.0V to 5.5V, F_{OSC} = 1 MHz with 10% Duty Cycle, C_{IN} = 0.1 µF, V_{IN} for typical values = 5.0V, T_A = -40°C to +125°C.

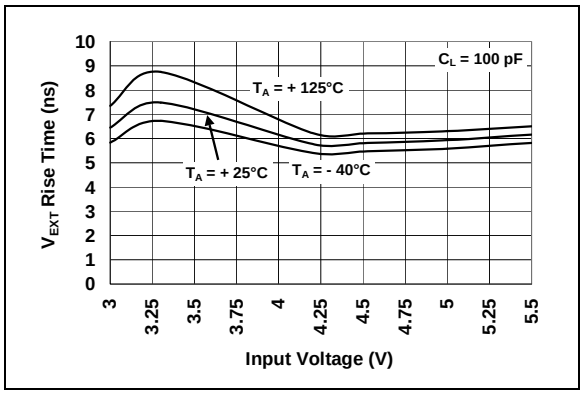


FIGURE 2-7: *V_{EXT} Rise Time vs. Input Voltage.*

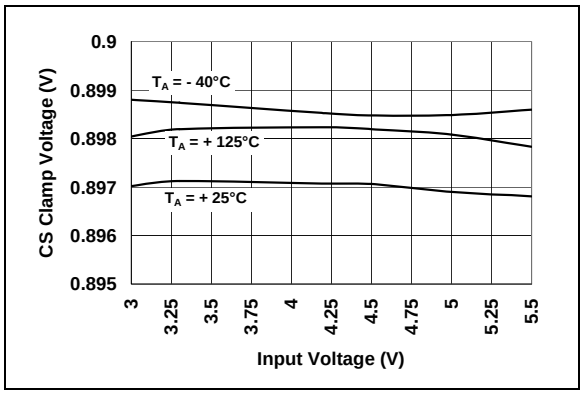


FIGURE 2-10: *Current Sense Clamp Voltage vs. Input Voltage (MCP1630).*

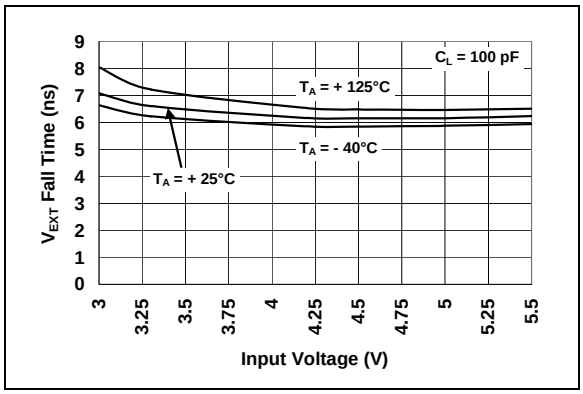


FIGURE 2-8: *V_{EXT} Fall Time vs. Input Voltage.*

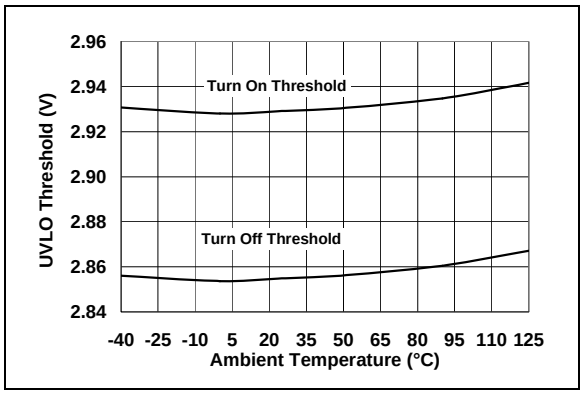


FIGURE 2-11: *Undervoltage Lockout vs. Temperature.*

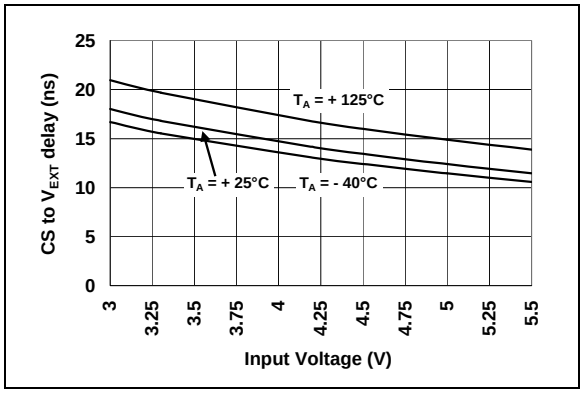


FIGURE 2-9: *Current Sense to V_{EXT} Delay vs. Input Voltage (MCP1630).*

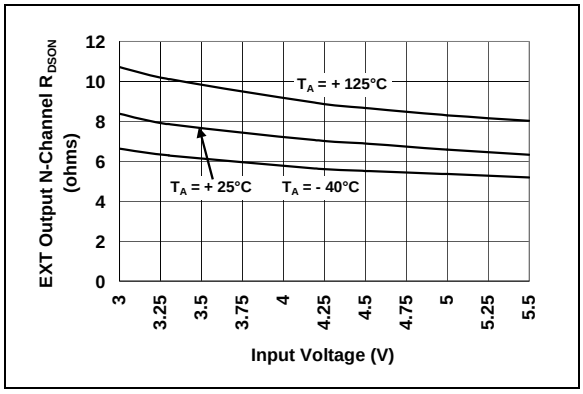


FIGURE 2-12: *EXT Output N-channel R_{DSON} vs. Input Voltage.*

Note: Unless otherwise noted, V_{IN} = 3.0V to 5.5V, F_{OSC} = 1 MHz with 10% Duty Cycle, C_{IN} = 0.1 µF, V_{IN} for typical values = 5.0V, T_A = -40°C to +125°C.

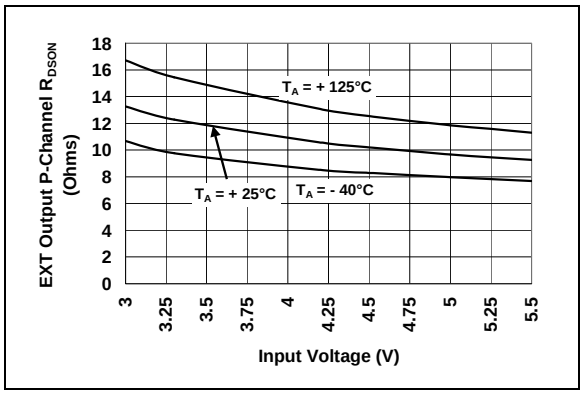


FIGURE 2-13: *EXT Output P-channel R_{DSON} vs. Input Voltage.*

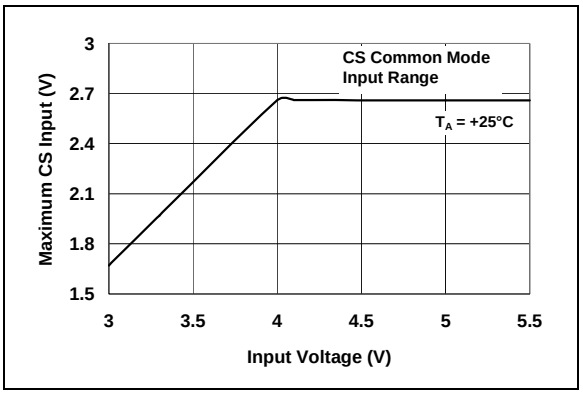


FIGURE 2-16: *Current Sense Common Mode Input Voltage Range vs. Input Voltage (MCP1630V).*

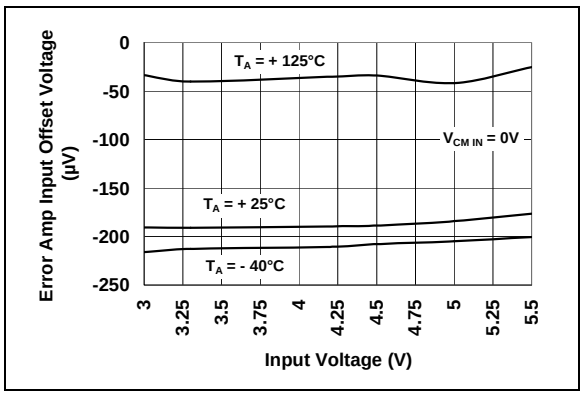


FIGURE 2-14: *Error Amplifier Input Offset Voltage vs. Input Voltage.*

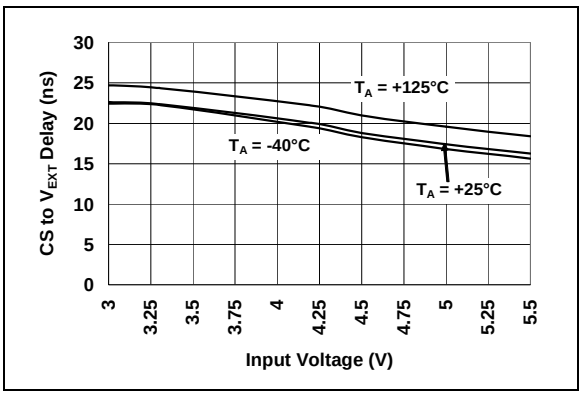


FIGURE 2-17: *Current Sense to V_{EXT} Delay vs. Input Voltage (MCP1630V).*

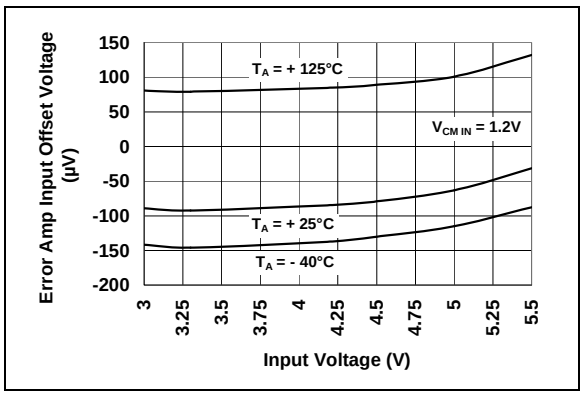


FIGURE 2-15: *Error Amplifier Input Offset Voltage vs. Input Voltage.*

© 2004-2013 Microchip Technology Inc.

3.0 MCP1630 PIN DESCRIPTIONS

The descriptions of the pins are listed in Table 3-1.

TABLE 3-1: PIN FUNCTION TABLE

DFN/MSOP	Name	Function
1	COMP	Error Amplifier Output pin
2	FB	Error Amplifier Inverting Input
3	CS	Current Sense Input pin (MCP1630) or Voltage Ramp Input pin (MCP1630V)
4	OSC IN	Oscillator Input pin
5	GND	Circuit Ground pin
6	V_{EXT}	External Driver Output pin
7	V_{IN}	Input Bias pin
8	V_{REF}	Reference Voltage Input pin

3.1 Error Amplifier Output Pin (COMP)

COMP is an internal error amplifier output pin. External compensation is connected from the FB pin to the COMP pin for control-loop stabilization. An internal voltage clamp is used to limit the maximum COMP pin voltage to 2.7V (typ.). This clamp is used to set the maximum peak current in the power system switch by setting a maximum limit on the CS input for Peak Current mode control systems.

3.2 Error Amplifier Inverting Input (FB)

FB is an internal error amplifier inverting input pin. The output (voltage or current) is sensed and fed back to the FB pin for regulation. Inverting or negative feedback is used.

3.3 Current Sensing Input (CS)

CS is the current sense input pin used for cycle-by-cycle control for Peak Current mode converters. The MCP1630 is typically used for sensed current applications to reduce the current sense signal, thus reducing power dissipation.

For Voltage mode or Average Current mode applications, a ramp is used to compare the error amplifier output voltage with producing the PWM duty cycle. For applications that require higher signal levels, the MCP1630V is used to increase the level from a maximum of 0.9V (MCP1630) to 2.7V (MCP1630V). The common mode voltage range for the MCP1630V CS input is V_{IN}-1.4V. For normal PWM operation, the CS input should be less than or equal to V_{IN} - 1.4V at all times.

3.4 Oscillator Input (OSC)

OSC is an external oscillator input pin. Typically, a microcontroller I/O pin is used to generate the OSC input. When high, the output driver pin (V_{EXT}) is driven low. The high-to-low transition initiates the start of a new cycle. The duty cycle of the OSC input pin determines the maximum duty cycle of the power converter. For example, if the OSC input is low for 75% of the time and high for 25% of the time, the duty cycle range for the power converter is 0% to 75% maximum.

3.5 Ground (GND)

Connect the circuit ground to the GND pin. For most applications, this should be connected to the analog or quiet ground plane. Noise on this ground can affect the sensitive cycle-by-cycle comparison between the CS input and the error amplifier output.

3.6 External Driver Output Pin (V_{EXT})

V_{EXT} is an external driver output pin, used to determine the power system duty cycle. For high-power or high-side drives, this output should be connected to the logic-level input of the MOSFET driver. For low-power, low-side applications, the V_{EXT} pin can be used to directly drive the gate of an N-channel MOSFET.

3.7 Input Bias Pin (V_{IN})

V_{IN} is an input voltage pin. Connect the input voltage source to the V_{IN} pin. For normal operation, the voltage on the V_{IN} pin should be between +3.0V and +5.5V. A 0.1 µF bypass capacitor should be connected between the V_{IN} pin and the GND pin.

3.8 Reference Voltage Input (V_{REF})

V_{REF} is an external reference input pin used to regulate the output of the power system. By changing the V_{REF} input, the output (voltage or current) of the power system can be changed. The reference voltage can range from 0V to V_{IN} (rail-to-rail).

© 2004-2013 Microchip Technology Inc.

4.0 DETAILED DESCRIPTION

4.1 Device Overview

The MCP1630 is comprised of a high-speed comparator, high-bandwidth amplifier and logic gates that can be combined with a PIC MCU to develop an advanced programmable power supply. The oscillator and reference voltage inputs are generated by the PIC MCU so that switching frequency, maximum duty cycle and output voltage are programmable. Refer to Figure 4-1.

4.2 PWM

The V_{EXT} output of the MCP1630/V is determined by the output level of the internal high-speed comparator and the level of the external oscillator. When the oscillator level is high, the PWM output (V_{EXT}) is forced low. When the external oscillator is low, the PWM output is determined by the output level of the internal high-speed comparator. During UVLO, the V_{EXT} pin is held in the low state. During overtemperature operation, the V_{EXT} pin is high-impedance (100 kΩ to ground).

4.3 Normal Cycle by Cycle Control

The beginning of a cycle is defined when OSC IN transitions from a high state to a low state. For normal operation, the state of the high-speed comparator output (R) is low and the $\overline{Q}$ output of the latch is low. On the OSC IN high-to-low transition, the S and R inputs to the high-speed latch are both low and the $\overline{Q}$ output will remain unchanged (low). The output of the OR gate (V_{DRIVE}) will transition from a high state to a low state, turning on the internal P-channel drive transistor in the output stage of the PWM. This will change the PWM output (V_{EXT}) from a low state to a high state, turning on the power-train external switch and ramping current in the power-train magnetic device.

The sensed current in the magnetic device is fed into the CS input (shown as a ramp) and increases linearly. Once the sensed current ramp (MCP1630) reaches the same voltage level as 1/3 of the EA output, the comparator output (R) changes states (low-to-high) and resets the PWM latch. The $\overline{Q}$ output transitions from a low state to a high state, turning on the N-channel MOSFET in the output stage, which turns off the V_{EXT} drive to the external MOSFET driver terminating the duty cycle. The OSC IN will transition from a low state to a high state while the V_{EXT} pin remains unchanged. If the CS input ramp had never reached the same level as 1/3 of the error amplifier output, the low-to-high transition on OSC IN would terminate the duty cycle and this would be considered maximum duty cycle. In either case, while OSC IN is high, the V_{EXT} drive pin is low, turning off the external power-train switch. The next cycle will start on the transition of the OSC IN pin from a high state to a low state.

For Voltage mode or Average Current mode applications that utilize a large signal ramp at the CS input, the MCP1630V is used to provide more signal (2.7V typ.). The operation of the PWM does not change.

4.4 Error Amp/Comparator Current Limit Function

The internal amplifier is used to create an error output signal that is determined by the external V_{REF} input and the power supply output fed back into the FB pin. The error amplifier output is rail-to-rail and clamped by a precision 2.7V. The output of the error amplifier is then divided down 3:1 (MCP1630) and connected to the inverting input of the high-speed comparator. Since the maximum output of the error amplifier is 2.7V, the maximum input to the inverting pin of the high-speed comparator is 0.9V. This sets the peak current limit for the switching power supply.

For the MCP1630V, the maximum error amplifier output is still 2.7V. However, the resistor divider is removed, raising the maximum input signal level at the high-speed comparator inverting input (CS) to 2.7V.

As the output load current demand increases, the error amplifier output increases, causing the inverting input pin of the high-speed comparator to increase. Eventually, the output of the error amplifier will hit the 2.7V clamp, limiting the input of the high-speed comparator to 0.9V max (MCP1630). Even if the FB input continues to decrease (calling for more current), the inverting input is limited to 0.9V. By limiting the inverting input to 0.9V, the current-sense input (CS) is limited to 0.9V, thus limiting the output current of the power supply.

For Voltage mode control, the error amplifier output will increase as input voltage decreases. A voltage ramp is used instead of sensed inductor current at the CS input of the MCP1630V. The 3:1 internal error amplifier output resistor divider is removed in the MCP1630V option to increase the maximum signal level input to 2.7V (typ.).

4.5 0% Duty Cycle Operation

The duty cycle of the V_{EXT} output is capable of reaching 0% when the FB pin is held higher than the V_{REF} pin (inverting error amplifier). This is accomplished by the rail-to-rail output capability of the error amplifier and the offset voltage of the high-speed comparator. The minimum error amplifier output voltage, divided by three, is less than the offset voltage of the high-speed comparator. In the case where the output voltage of the converter is above the desired regulation point, the FB input will be above the V_{REF} input and the error amplifier will be pulled to the bottom rail (GND). This low voltage is divided down 3:1 by the 2R and 1R resistor (MCP1630) and connected to the input of the high-speed comparator. This voltage will be low enough so that there is no triggering of the comparator, allowing narrow pulse widths at V_{EXT}.

© 2004-2013 Microchip Technology Inc.

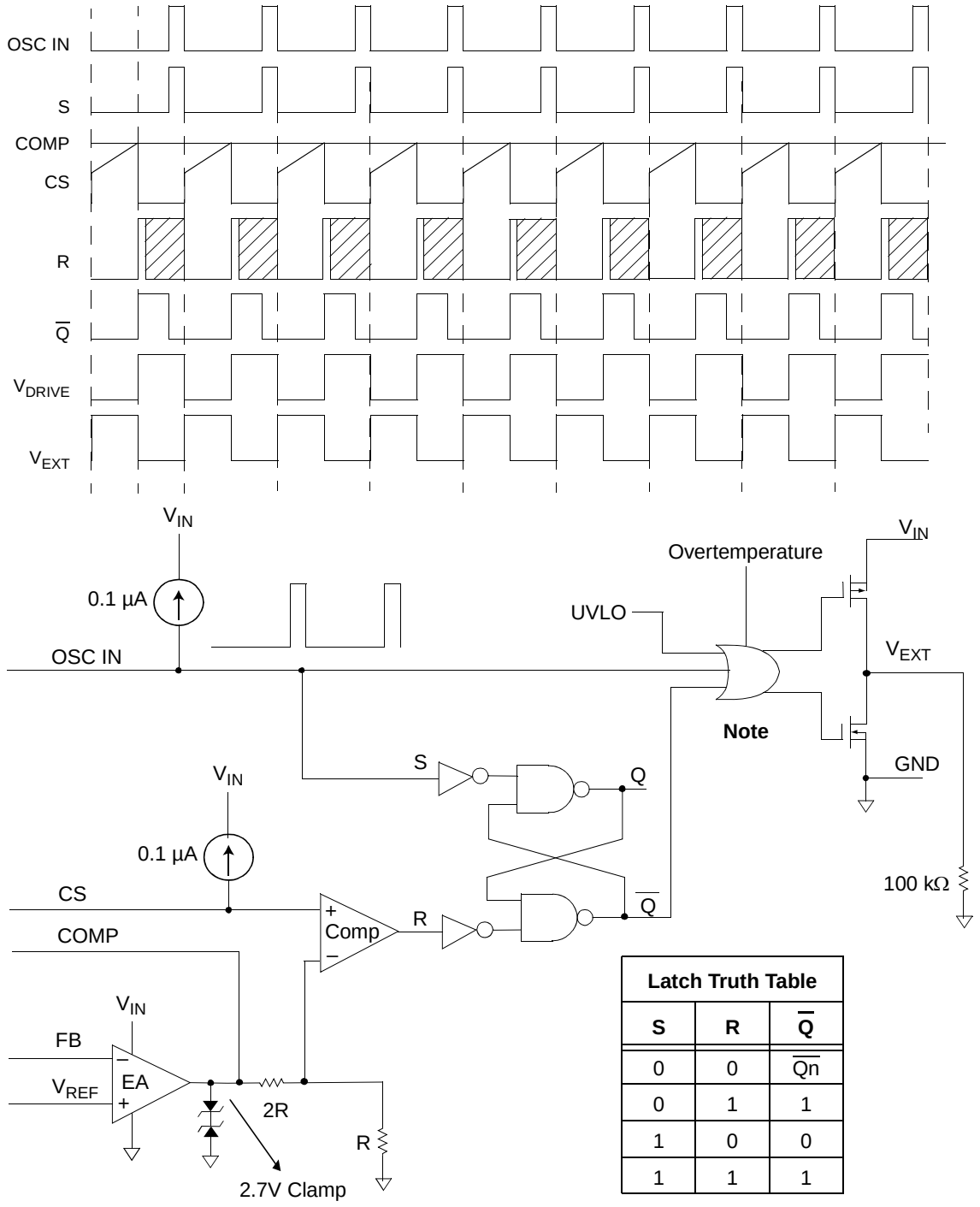
4.6 Undervoltage Lockout (UVLO)

When the input voltage (V_{IN}) is less than the UVLO threshold, the V_{EXT} is held in the low state. This will ensure that, if the voltage is not adequate to operate the MCP1630/V, the main power supply switch will be held in the off state. When the UVLO threshold is exceeded, there is some hysteresis in the input voltage prior to the UVLO off threshold being reached. The typical hysteresis is 75 mV. Typically, the MCP1630 will not start operating until the input voltage at V_{IN} is between 3.0V and 3.1V.

4.7 Overtemperature Protection

To protect the V_{EXT} output if shorted to V_{IN} or GND, the MCP1630/V V_{EXT} output will be high-impedance if the junction temperature is above the thermal shutdown threshold. There is an internal 100 kΩ pull-down resistor connected from V_{EXT} to ground to provide some pull-down during overtemperature conditions. The protection is set to 150°C (typ.), with a hysteresis of 18°C.

MCP1630 High-Speed PWM Timing Diagram



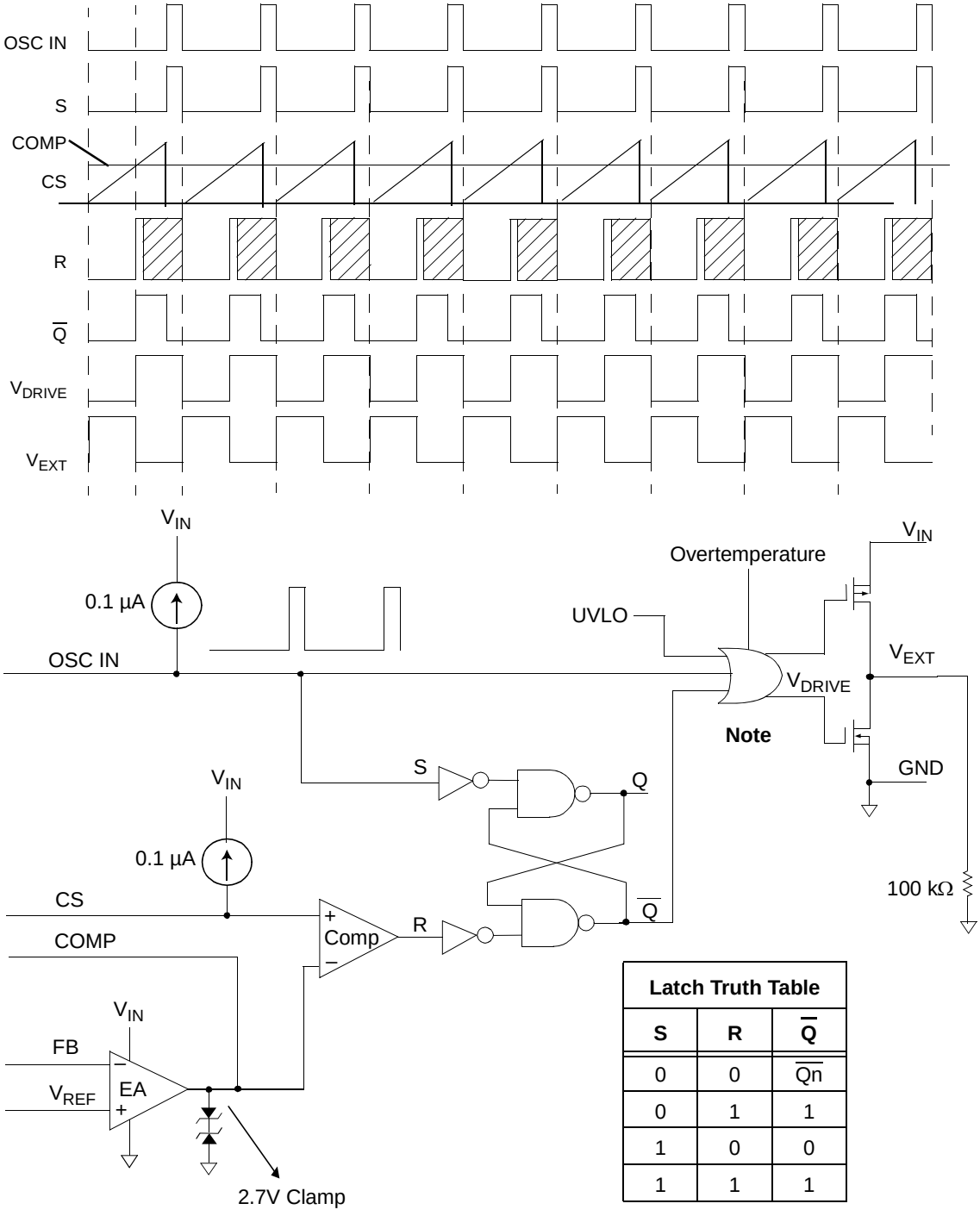
Latch Truth Table		
S	**R**	**$\overline{Q}$**
0	0	$\overline{Qn}$
0	1	1
1	0	0
1	1	1

Note: During overtemperature, V_{EXT} driver is high-impedance.

FIGURE 4-1: *Cycle-by-Cycle Timing Diagram (MCP1630).*

© 2004-2013 Microchip Technology Inc.

MCP1630V High-Speed PWM Timing Diagram



Latch Truth Table		
S	**R**	**$\overline{Q}$**
0	0	$\overline{Qn}$
0	1	1
1	0	0
1	1	1

Note: During overtemperature, V_{EXT} driver is high-impedance.

FIGURE 4-2: *Cycle-by-Cycle Timing Diagram (MCP1630V).*

5.0 APPLICATION CIRCUITS/ISSUES

5.1 Typical Applications

The MCP1630/V high-speed PWM can be used for any circuit topology and power-train application when combined with a microcontroller. Intelligent, cost-effective power systems can be developed for applications that require multiple outputs, multiple phases, adjustable outputs, temperature monitoring and calibration.

5.2 NiMH Battery Charger Application

A typical NiMH battery charger application is shown in the **"Typical Application Circuit – MCP1630"** of this data sheet. In that example, a Single-Ended Primary Inductive Converter (SEPIC) is used to provide a constant charge current to the series-connected batteries. The MCP1630 is used to regulate the charge current by monitoring the current through the battery sense resistor and providing the proper pulse width.

The PIC16F818 monitors the battery voltage to provide a termination to the charge current. Additional features (trickle charge, fast charge, overvoltage protection, etc.) can be added to the system using the programmability of the microcontroller and the flexibility of the MCP1630.

5.3 Bidirectional Power Converter

A bidirectional Li-Ion charger/buck regulator is shown in the **"Typical Application Circuit"** of the this data sheet. In this example, a synchronous, bidirectional power converter example is shown using the MCP1630V. In this application, when the ac-dc input power is present, the bidirectional power converter is used to charge 4-series Li-Ion batteries by boosting the input voltage. When ac-dc power is removed, the bidirectional power converter bucks the battery voltage down to provide a dc bus for system power. By using this method, a single power train is capable of charging 4-series cell Li-Ion batteries and efficiently converting the battery voltage down to a low, usable voltage.

5.4 Multiple Output Converters

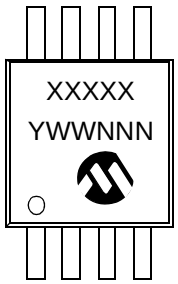
By using additional MCP1630 devices, multiple output converters can be developed using a single MCU. If a two-output converter is desired, the MCU can provide two PWM outputs that are phased 180° apart. This will reduce the input ripple current to the source and eliminate beat frequencies.

© 2004-2013 Microchip Technology Inc.

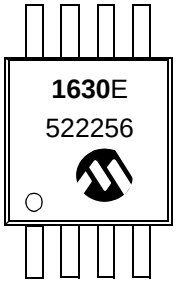
6.0 PACKAGING INFORMATION

6.1 Package Marking Information

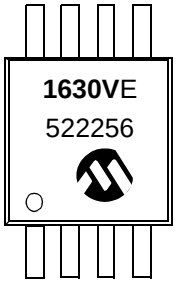
8-Lead MSOP



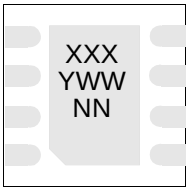
Example:



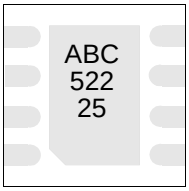
Example:



8-Lead DFN (2 mm x 3 mm)



Example:



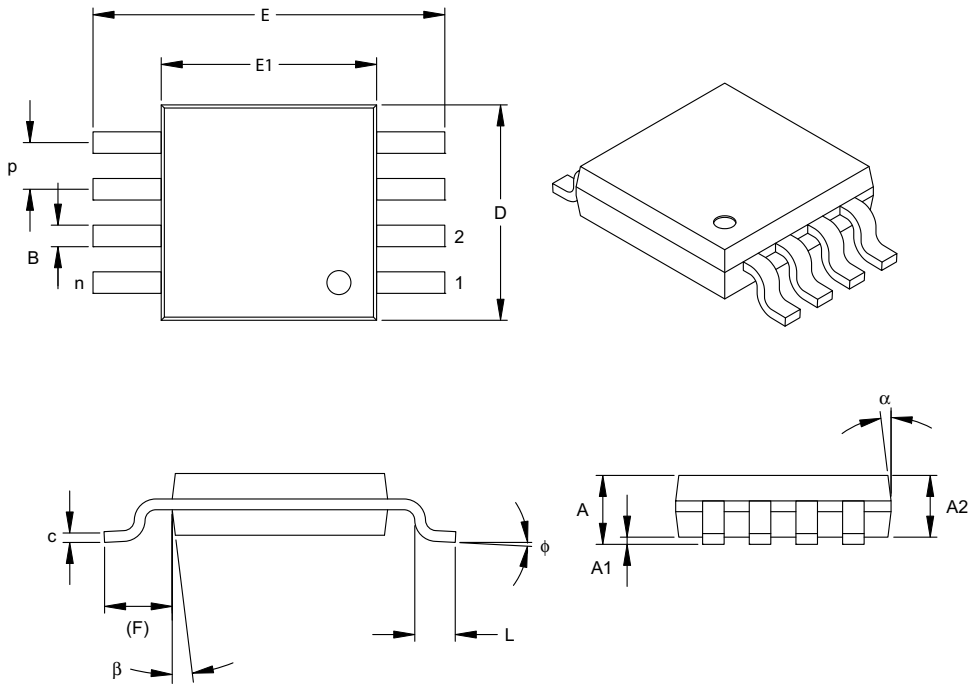
For DFN samples, contact your Microchip Sales Office for availability..

Legend:	XX...X	Customer-specific information
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week ‘01’)
	NNN	Alphanumeric traceability code
	(e3)	Pb-free JEDEC designator for Matte Tin (Sn)
	*	This package is Pb-free. The Pb-free JEDEC designator ((e3)) can be found on the outer packaging for this package.

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.

8-Lead Plastic Micro Small Outline Package (MS) (MSOP)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		INCHES			MILLIMETERS*		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		8			8	
Pitch	p		.026 BSC			0.65 BSC	
Overall Height	A	-	-	.043	-	-	1.10
Molded Package Thickness	A2	.030	.033	.037	0.75	0.85	0.95
Standoff	A1	.000	-	.006	0.00	-	0.15
Overall Width	E		.193 TYP.			4.90 BSC	
Molded Package Width	E1		.118 BSC			3.00 BSC	
Overall Length	D		.118 BSC			3.00 BSC	
Foot Length	L	.016	.024	.031	0.40	0.60	0.80
Footprint (Reference)	F		.037 REF			0.95 REF	
Foot Angle	ϕ	0°	-	8°	0°	-	8°
Lead Thickness	c	.003	.006	.009	0.08	-	0.23
Lead Width	B	.009	.012	.016	0.22	-	0.40
Mold Draft Angle Top	α	5°	-	15°	5°	-	15°
Mold Draft Angle Bottom	β	5°	-	15°	5°	-	15°

*Controlling Parameter

Notes:

Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" (0.254mm) per side.

JEDEC Equivalent: MO-187

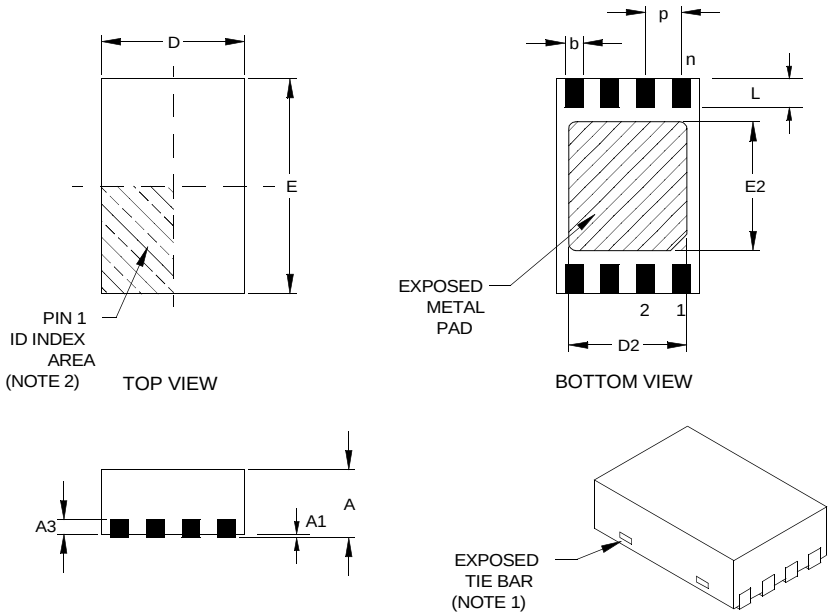
Drawing No. C04-111

© 2004-2013 Microchip Technology Inc.

8-Lead Plastic Dual Flat No Lead Package (MC) 2x3x0.9 mm Body (DFN) – Saw Singulated

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging

For DFN samples, contact your Microchip Sales Office for availability..



Units		INCHES			MILLIMETERS*		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		8			8	
Pitch	p		.020 BSC			0.50 BSC	
Overall Height	A	.031	.035	.039	0.80	0.90	1.00
Standoff	A1	.000	.001	.002	0.00	0.02	0.05
Contact Thickness	A3		.008 REF.			0.20 REF.	
Overall Length	D		.079 BSC			2.00 BSC	
Exposed Pad Length (Note 3)	D2	.055	.065	.067	1.39	1.65	1.70
Overall Width	E		.118 BSC			3.00 BSC	
Exposed Pad Width (Note 3)	E2	.047	.059	.061	1.20	1.50	1.55
Contact Width	b	.008	.010	.012	0.20	0.25	0.30
Contact Length	L	.012	.016	.020	0.30	0.40	0.50

*Controlling Parameter

Notes:

1. BSC: Basic Dimension. Theoretically exact value shown without tolerances.
   See ASME Y14.5M
2. REF: Reference Dimension, usually without tolerance, for information purposes only.
   See ASME Y14.5M

Exposed pad varies according to die attach paddle size.

Package may have one or more exposed tie bars at ends.

Pin 1 visual index feature may vary, but must be located within the hatched area.

JEDEC equivalent: M0-229

Drawing No. C04-123, Revised 05-05-05

NOTES:

© 2004-2013 Microchip Technology Inc.

APPENDIX A: REVISION HISTORY

Revision C (January 2013)

- Added a note to each package outline drawing.

Revision B (June 2005)

The following is the list of modifications:

1. Added MCP1630V device information throughout data sheet
2. Added DFN package information throughout data sheet.
3. Added Appendix A: Revision History.

Revision A (June 2004)

- Original Release of this Document.

NOTES:

© 2004-2013 Microchip Technology Inc.

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

PART NO.	X	/XX
Device	Temperature Range	Package

Device:	MCP1630:	High-Speed, Microcontroller-Adaptable, PWM
	MCP1630T:	High-Speed, Microcontroller-Adaptable, PWM (Tape and Reel)
Temperature Range:	E =	-40°C to +125°C
Package:	MC *=	Dual Flat, No Lead (2x3mm Body), 8-lead
	MS =	Plastic MSOP, 8-lead

* For DFN samples, contact your Microchip Sales Office for availability.

Examples:

a) MCP1630-E/MS: Extended Temperature, 8LD MSOP package.

b) MCP1630T-E/MS: Tape and Reel Extended Temperature, 8LD MSOP package.

c) MCP1630-E/MC: Extended Temperature, 8LD DFN package.

a) MCP1630V-E/MS: Extended Temperature, 8LD MSOP package.

b) MCP1630VT-E/MS: Tape and Reel Extended Temperature, 8LD MSOP package.

c) MCP1630V-E/MC: Extended Temperature, 8LD DFN package.

NOTES:

© 2004-2013 Microchip Technology Inc.

Note the following details of the code protection feature on Microchip devices:

- Microchip products meet the specification contained in their particular Microchip Data Sheet.
- Microchip believes that its family of products is one of the most secure families of its kind on the market today, when used in the intended manner and under normal conditions.
- There are dishonest and possibly illegal methods used to breach the code protection feature. All of these methods, to our knowledge, require using the Microchip products in a manner outside the operating specifications contained in Microchip's Data Sheets. Most likely, the person doing so is engaged in theft of intellectual property.
- Microchip is willing to work with the customer who is concerned about the integrity of their code.
- Neither Microchip nor any other semiconductor manufacturer can guarantee the security of their code. Code protection does not mean that we are guaranteeing the product as "unbreakable."

Code protection is constantly evolving. We at Microchip are committed to continuously improving the code protection features of our products. Attempts to break Microchip's code protection feature may be a violation of the Digital Millennium Copyright Act. If such acts allow unauthorized access to your software or other copyrighted work, you may have a right to sue for relief under that Act.

Information contained in this publication regarding device applications and the like is provided only for your convenience and may be superseded by updates. It is your responsibility to ensure that your application meets with your specifications. MICROCHIP MAKES NO REPRESENTATIONS OR WARRANTIES OF ANY KIND WHETHER EXPRESS OR IMPLIED, WRITTEN OR ORAL, STATUTORY OR OTHERWISE, RELATED TO THE INFORMATION, INCLUDING BUT NOT LIMITED TO ITS CONDITION, QUALITY, PERFORMANCE, MERCHANTABILITY OR FITNESS FOR PURPOSE**.** Microchip disclaims all liability arising from this information and its use. Use of Microchip devices in life support and/or safety applications is entirely at the buyer's risk, and the buyer agrees to defend, indemnify and hold harmless Microchip from any and all damages, claims, suits, or expenses resulting from such use. No licenses are conveyed, implicitly or otherwise, under any Microchip intellectual property rights.

Trademarks

The Microchip name and logo, the Microchip logo, dsPIC, FlashFlex, KEELOQ, KEELOQ logo, MPLAB, PIC, PICmicro, PICSTART, PIC^{32} logo, rfPIC, SST, SST Logo, SuperFlash and UNI/O are registered trademarks of Microchip Technology Incorporated in the U.S.A. and other countries.

FilterLab, Hampshire, HI-TECH C, Linear Active Thermistor, MTP, SEEVAL and The Embedded Control Solutions Company are registered trademarks of Microchip Technology Incorporated in the U.S.A.

Silicon Storage Technology is a registered trademark of Microchip Technology Inc. in other countries.

Analog-for-the-Digital Age, Application Maestro, BodyCom, chipKIT, chipKIT logo, CodeGuard, dsPICDEM, dsPICDEM.net, dsPICworks, dsSPEAK, ECAN, ECONOMONITOR, FanSense, HI-TIDE, In-Circuit Serial Programming, ICSP, Mindi, MiWi, MPASM, MPF, MPLAB Certified logo, MPLIB, MPLINK, mTouch, Omniscient Code Generation, PICC, PICC-18, PICDEM, PICDEM.net, PICkit, PICtail, REAL ICE, rfLAB, Select Mode, SQI, Serial Quad I/O, Total Endurance, TSHARC, UniWinDriver, WiperLock, ZENA and Z-Scale are trademarks of Microchip Technology Incorporated in the U.S.A. and other countries.

SQTP is a service mark of Microchip Technology Incorporated in the U.S.A.

GestIC and ULPP are registered trademarks of Microchip Technology Germany II GmbH & Co. & KG, a subsidiary of Microchip Technology Inc., in other countries.

All other trademarks mentioned herein are property of their respective companies.

© 2004-2013, Microchip Technology Incorporated, Printed in the U.S.A., All Rights Reserved.

Printed on recycled paper.

ISBN: 9781620769140

QUALITY MANAGEMENT SYSTEM
CERTIFIED BY DNV
ISO/TS 16949

Microchip received ISO/TS-16949:2009 certification for its worldwide headquarters, design and wafer fabrication facilities in Chandler and Tempe, Arizona; Gresham, Oregon and design centers in California and India. The Company's quality system processes and procedures are for its PIC® MCUs and dsPIC® DSCs, KEELOQ® code hopping devices, Serial EEPROMs, microperipherals, nonvolatile memory and analog products. In addition, Microchip's quality system for the design and manufacture of development systems is ISO 9001:2000 certified.

Worldwide Sales and Service

AMERICAS

Corporate Office
2355 West Chandler Blvd.
Chandler, AZ 85224-6199
Tel: 480-792-7200
Fax: 480-792-7277
Technical Support:
http://www.microchip.com/support
Web Address:
www.microchip.com

Atlanta
Duluth, GA
Tel: 678-957-9614
Fax: 678-957-1455

Boston
Westborough, MA
Tel: 774-760-0087
Fax: 774-760-0088

Chicago
Itasca, IL
Tel: 630-285-0071
Fax: 630-285-0075

Cleveland
Independence, OH
Tel: 216-447-0464
Fax: 216-447-0643

Dallas
Addison, TX
Tel: 972-818-7423
Fax: 972-818-2924

Detroit
Farmington Hills, MI
Tel: 248-538-2250
Fax: 248-538-2260

Indianapolis
Noblesville, IN
Tel: 317-773-8323
Fax: 317-773-5453

Los Angeles
Mission Viejo, CA
Tel: 949-462-9523
Fax: 949-462-9608

Santa Clara
Santa Clara, CA
Tel: 408-961-6444
Fax: 408-961-6445

Toronto
Mississauga, Ontario,
Canada
Tel: 905-673-0699
Fax: 905-673-6509

ASIA/PACIFIC

Asia Pacific Office
Suites 3707-14, 37th Floor
Tower 6, The Gateway
Harbour City, Kowloon
Hong Kong
Tel: 852-2401-1200
Fax: 852-2401-3431

Australia - Sydney
Tel: 61-2-9868-6733
Fax: 61-2-9868-6755

China - Beijing
Tel: 86-10-8569-7000
Fax: 86-10-8528-2104

China - Chengdu
Tel: 86-28-8665-5511
Fax: 86-28-8665-7889

China - Chongqing
Tel: 86-23-8980-9588
Fax: 86-23-8980-9500

China - Hangzhou
Tel: 86-571-2819-3187
Fax: 86-571-2819-3189

China - Hong Kong SAR
Tel: 852-2943-5100
Fax: 852-2401-3431

China - Nanjing
Tel: 86-25-8473-2460
Fax: 86-25-8473-2470

China - Qingdao
Tel: 86-532-8502-7355
Fax: 86-532-8502-7205

China - Shanghai
Tel: 86-21-5407-5533
Fax: 86-21-5407-5066

China - Shenyang
Tel: 86-24-2334-2829
Fax: 86-24-2334-2393

China - Shenzhen
Tel: 86-755-8864-2200
Fax: 86-755-8203-1760

China - Wuhan
Tel: 86-27-5980-5300
Fax: 86-27-5980-5118

China - Xian
Tel: 86-29-8833-7252
Fax: 86-29-8833-7256

China - Xiamen
Tel: 86-592-2388138
Fax: 86-592-2388130

China - Zhuhai
Tel: 86-756-3210040
Fax: 86-756-3210049

ASIA/PACIFIC

India - Bangalore
Tel: 91-80-3090-4444
Fax: 91-80-3090-4123

India - New Delhi
Tel: 91-11-4160-8631
Fax: 91-11-4160-8632

India - Pune
Tel: 91-20-2566-1512
Fax: 91-20-2566-1513

Japan - Osaka
Tel: 81-6-6152-7160
Fax: 81-6-6152-9310

Japan - Tokyo
Tel: 81-3-6880- 3770
Fax: 81-3-6880-3771

Korea - Daegu
Tel: 82-53-744-4301
Fax: 82-53-744-4302

Korea - Seoul
Tel: 82-2-554-7200
Fax: 82-2-558-5932 or
82-2-558-5934

Malaysia - Kuala Lumpur
Tel: 60-3-6201-9857
Fax: 60-3-6201-9859

Malaysia - Penang
Tel: 60-4-227-8870
Fax: 60-4-227-4068

Philippines - Manila
Tel: 63-2-634-9065
Fax: 63-2-634-9069

Singapore
Tel: 65-6334-8870
Fax: 65-6334-8850

Taiwan - Hsin Chu
Tel: 886-3-5778-366
Fax: 886-3-5770-955

Taiwan - Kaohsiung
Tel: 886-7-213-7828
Fax: 886-7-330-9305

Taiwan - Taipei
Tel: 886-2-2508-8600
Fax: 886-2-2508-0102

Thailand - Bangkok
Tel: 66-2-694-1351
Fax: 66-2-694-1350

EUROPE

Austria - Wels
Tel: 43-7242-2244-39
Fax: 43-7242-2244-393

Denmark - Copenhagen
Tel: 45-4450-2828
Fax: 45-4485-2829

France - Paris
Tel: 33-1-69-53-63-20
Fax: 33-1-69-30-90-79

Germany - Munich
Tel: 49-89-627-144-0
Fax: 49-89-627-144-44

Italy - Milan
Tel: 39-0331-742611
Fax: 39-0331-466781

Netherlands - Drunen
Tel: 31-416-690399
Fax: 31-416-690340

Spain - Madrid
Tel: 34-91-708-08-90
Fax: 34-91-708-08-91

UK - Wokingham
Tel: 44-118-921-5869
Fax: 44-118-921-5820

11/29/12

© 2004-2013 Microchip Technology Inc.

Общество с ограниченной ответственностью «МосЧип» ИНН 7719860671 / КПП 771901001
Адрес: 105318, г.Москва, ул.Щербаковская д.3, офис 1107

Данный компонент на территории Российской Федерации

Вы можете приобрести в компании MosChip.

Для оперативного оформления запроса Вам необходимо перейти по данной ссылке:

http://moschip.ru/get-element

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

Офис по работе с юридическими лицами:

105318, г.Москва, ул.Щербаковская д.3, офис 1107, 1118, ДЦ «Щербаковский»

Телефон: +7 495 668-12-70 (многоканальный)

Факс: +7 495 668-12-70 (доб.304)

E-mail: info@moschip.ru

Skype отдела продаж:
moschip.ru
moschip.ru_4
moschip.ru_6
moschip.ru_9